

AMENDMENTS TO THE CLAIMS

The following listing of claims replaces all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) An electronic component ~~including, comprising:~~
a plurality of circuit elements on one surface of a substrate, the circuit elements being one of resistive elements and dielectrics;
a plurality of electrode pairs on the one surface of the substrate, the electrode pairs being respectively connected to the circuit elements;
an overcoat covering the circuit elements and the electrode pairs while partially exposing a part of each electrode of the electrode pairs, the exposed parts providing a plurality of lands; and
a plurality of conductive balls respectively fixedly bonded to the lands by fixedly bonded members,
the plurality of lands include first lands and second lands, and the second lands have a larger land area than the first lands,
the conductive balls are substantially equal in size to one another,
the circuit elements connected to the electrode pairs with the second lands are offset such that the circuit elements are laterally displaced from a shortest path between a center of each electrode of the electrode pairs in a plan view.
~~on one surface of a substrate, a plurality of circuit elements and external terminals for the circuit elements, each of the external terminals consisting of a conductive protrusion, wherein~~

~~each of the circuit elements includes, as constituent elements, a pair of electrodes and a resistive element or a dielectric contacting with the pair of electrodes, said each circuit element is covered with an overcoat while the electrodes are partially exposed as lands, said conductive protrusion includes a fixedly bonding member, said conductive protrusion is fixedly bonded to each of said lands by the fixedly bonding member, at least three of said lands are larger in area than the other lands, the electronic component can stand alone while the conductive protrusion contacts with a flat if the conductive protrusion is fixedly bonded only to each of the larger-area lands, and the conductive protrusions are all formed by fixedly bonding conductive balls substantially equal in size to entire surfaces of the respective lands.~~

2. (Currently Amended) The electronic component according to claim 1, wherein

~~each of the larger-area~~second lands is located at a position proximate to an external end of the substrate.

3. (Currently Amended) The electronic component according to claim 1, wherein

~~the conductive balls are fixedly bonded to the entire surfaces of the respective lands by the fixedly bonding member~~ at each land has a size that is having an amount proportional to an area of each of the lands land so that the conductive balls are fixedly bonded to an entire surface of the each land.

4-5. (Cancelled)

6. (Currently Amended) The electronic component according to claim 1,
wherein

~~a size of the substrate~~ the second lands are larger in a direction of a longer side
of the substrate ~~is larger than a size of the substrate~~ in a direction of a shorter side of
the substrate ~~on each larger-area land~~.

7. (Currently Amended) The electronic component according to claim 1,
wherein

the substrate is a tetragonal substrate and one of the second lands is
located ~~each larger-area land is present in each of four corners~~ corner of ~~a~~ the tetragonal
substrate.

8. (Currently Amended) The electronic component according to claim 1,
wherein

the substrate is a tetragonal substrate and one of the second lands is
located ~~each larger-area land is present~~ at a position proximate to each of both external
ends of the tetragonal substrate in ~~a~~ the direction of ~~a~~ the shorter side of the tetragonal
substrate.

9. (Currently Amended) The electronic component according to claim 1,
wherein

~~each larger-area land is~~ the second lands are shaped as at least one of a tetragon, an ellipse, and a tetragon having four rounded corners.

10-13. (Cancelled)

14. (Currently Amended) The electronic component according to claim 1, wherein

~~each larger-area land consists of Metal Graze[®] material~~ the second lands include an Ag-Pd containing conductive paste, and an entire surface of each second larger-area land is covered with the fixedly bonding member.

15. (New) The electronic component according to claim 2, wherein the second lands are larger in a direction of a longer side of the substrate than in a direction of a shorter side of the substrate.

16. (New) The electronic component according to claim 3, wherein the second lands are larger in a direction of a longer side of the substrate larger in a direction of a shorter side of the substrate.

17. (New) The electronic component according to claim 2, wherein the substrate is a tetragonal substrate and one of the second lands is located in each corner of the tetragonal substrate.

18. (New) The electronic component according to claim 3, wherein the substrate is a tetragonal substrate and one of the second lands is located in each corner of the tetragonal substrate.

19. (New) The electronic component according to claim 4, wherein the substrate is a tetragonal substrate and one of the second lands is located in each corner of the tetragonal substrate.

20. (New) The electronic component according to claim 2, wherein the substrate is a tetragonal substrate and one of the second lands is located at a position proximate to each of both external ends of the tetragonal substrate in a direction of a shorter side of the tetragonal substrate.

21. (New) The electronic component according to claim 3, wherein the substrate is a tetragonal substrate and one of the second lands is located at a position proximate to each of both external ends of the tetragonal substrate in a direction of a shorter side of the tetragonal substrate.

22. (New) The electronic component according to claim 4, wherein the substrate is a tetragonal substrate and one of the second lands is located at a position proximate to each of both external ends of the tetragonal substrate in a direction of a shorter side of the tetragonal substrate.

23. (New) The electronic component according to claim 5, wherein
the substrate is a tetragonal substrate and one of the second lands is located at
a position proximate to each of both external ends of the tetragonal substrate in a
direction of a shorter side of the tetragonal substrate.

24. (New) The electronic component according to claim 2, wherein
the second lands are shaped as at least one of a tetragon, an ellipse, and a
tetragon having rounded corners.

25. (New) The electronic component according to claim 3, wherein
the second lands are shaped as at least one of a tetragon, an ellipse, and a
tetragon having rounded corners.

26. (New) The electronic component according to claim 4, wherein
the second lands are shaped as at least one of a tetragon, an ellipse, and a
tetragon having rounded corners.

27. (New) The electronic component according to claim 5, wherein
the second lands are shaped as at least one of a tetragon, an ellipse, and a
tetragon having rounded corners.

28. (New) The electronic component according to claim 6, wherein
the second lands are shaped as at least one of a tetragon, an ellipse, and a
tetragon having rounded corners.